IN THE SPECIFICATION:

Please replace paragraph **[0036]** with the following amended paragraph:

[0036] Generally, the loading robot 110 is disposed proximate the factory interface 108 and the processing module 112 to facilitate the transfer of substrates 122 therebetween. The factory interface 108 generally includes a cleaning module 114 and one or more substrate cassettes 116. An interface robot 118 is employed to transfer substrates 123 between the substrate cassettes 116, the cleaning module 114 and an input module 120. The input module 120 is positioned to facilitate transfer of substrates 123 between the processing module 112 and the factory interface 108 by the loading robot 110. An example of a factory interface that may be used to advantage is disclosed in United States Patent Application Serial No. 09/547,189, filed April 11, 2000, which has issued as United States Patent No. 6,361,422, issued March 26, 2003, and is assigned to common assignee Applied Materials, Inc., and which is hereby incorporated by reference.

Please replace paragraph **[0039]** with the following amended paragraph:

[0039] In one embodiment, the transfer station 122 comprises at least an input buffer station 128, an output buffer station 130, a transfer robot 132, and a load cup assembly 124. The transfer robot 132 has two gripper assemblies, each having pneumatic gripper fingers that grab the substrate 123 by the substrate's edge. The transfer robot 132 lifts the substrate 123 from the input buffer station 128 and rotates the gripper and substrate 123 to position the substrate 123 over the load cup assembly 134, then places the substrate 123 down onto the load cup assembly 124. An example of a transfer station that may be used to advantage is described by *Tobin* in United States Patent Application Serial No. 09/[[3]]414,771, filed October [[10]] 6, 1999, which has issued as United States Patent No. 6,156,124, issued December 5, 2000, and is assigned to common assignee Applied Materials, Inc., and which is hereby incorporated by reference.

Please replace paragraph **[0104]** with the following amended paragraph:

[0104] Another apparatus which may be used to practice the processes described herein and may be used or adapted for use in processing system 200 as shown in Figures 2 and 3 is more fully described in United States Patent Application Serial Number 09/770,559, filed January 26, 2001, which has issued as United States Patent No. 6,613,200, issued September 2, 2003, ~~each of~~ which [[are]] is incorporated herein by reference.

Please replace paragraph **[0123]** with the following amended paragraph:

[0123] In another aspect, the electrolyte solution may also comprise a base compound, such as potassium hydroxide (KOH) for example, to adjust the pH of the solution, which may be present in an amount up to about 70 percent by weight in volume of total solution and a phosphate system, such as ammonium dihydrogen phosphate ($NH_4H_2PO_4$), diammonium hydrogen phosphate ($(NH_4)_2HPO_4$), phosphoric acid, or a mixture thereof, in amounts between about 2 and about 30 percent by weight in volume of total solution. Dihydrogen phosphate and/or diammonium hydrogen phosphate may be present in amounts between about 15 and about 25 percent by weight in volume of total solution. Suitable electrolyte solutions are further disclosed in co-pending U.S. Patent Application Serial No.[[_____]] 10/032,275 (Applied Materials, Inc., Docket No. AMAT 5998), entitled, "Electrolyte Composition And Treatment For Electrolytic Chemical Mechanical Polishing," filed on December 21, 2001.